

## DC/DC CONVERTER APPLICATIONS

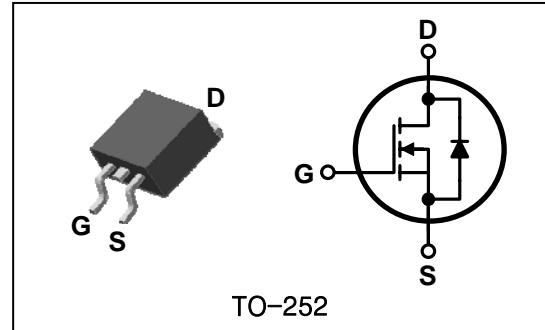
### Features

- High Voltage :  $BV_{DSS}=100V$ (Min.)
- Low  $C_{rss}$  :  $C_{rss}=130pF$ (Typ.)
- Low gate charge :  $Q_g=75nC$ (Typ.)
- Low  $R_{DS(ON)}$  :  $R_{DS(ON)}=26m\Omega$ (Max.)

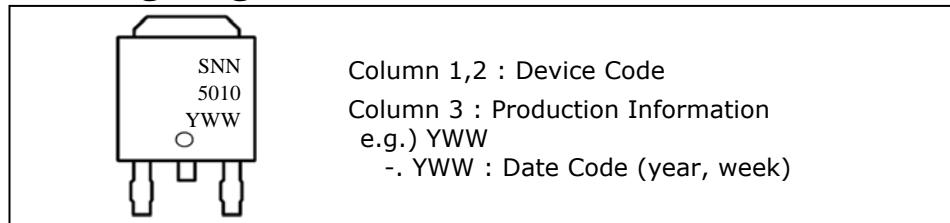
### Ordering Information

Type No.	Marking	Package Code
SNN5010D	SNN5010	TO-252

### PIN Connection



### Marking Diagram



### Absolute maximum ratings ( $T_c=25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	100	V
Gate-source voltage	$V_{GSS}$	$\pm 20$	V
Drain current (DC) *	$I_D$	( $T_c=25^\circ C$ )	A
		( $T_c=100^\circ C$ )	
Drain current (Pulsed) *	$I_{DM}$	150	A
Power dissipation	$P_D$	65	W
Avalanche current (Single)	$I_{AS}$	25	A
Single pulsed avalanche energy	$E_{AS}$	173	mJ
Avalanche current (Repetitive)	$I_{AR}$	50	A
Repetitive avalanche energy	$E_{AR}$	6.5	mJ
Junction temperature	$T_J$	150	$^\circ C$
Storage temperature range	$T_{stg}$	-55~150	

\* Limited by maximum junction temperature

Characteristic	Symbol	Typ.	Max.	Unit
Thermal resistance*	$R_{th(J-C)}$	-	1.92	$^\circ C/W$
	$R_{th(J-A)}$	-	62.5	

## Electrical Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$I_D=250\mu\text{A}, V_{GS}=0$	100	-	-	V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$	1.7	2.5	3.4	V
Drain-source cut-off current	$I_{\text{DSS}}$	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
		$V_{DS}=80\text{V}, V_{GS}=0\text{V}, T_J=125^\circ\text{C}$	-	-	100	
Gate leakage current	$I_{GSS}$	$V_{DS}=0\text{V}, V_{GS}=\pm20\text{V}$	-	-	$\pm100$	nA
Drain-source on-resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=25\text{A}$	-	21	26	$\text{m}\Omega$
		$V_{GS}=4.8\text{V}, I_D=1\text{A}$		130	200	
Forward transfer conductance ④	$g_{fs}$	$V_{DS}=40\text{V}, I_D=25\text{A}$	-	30	-	S
Input capacitance	$C_{iss}$	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$	-	2100	2310	$\text{pF}$
Output capacitance	$C_{oss}$		-	640	704	
Reverse transfer capacitance	$C_{rss}$		-	130	143	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50\text{V}, I_D=50\text{A}$ $R_G=25\Omega$	-	25	-	$\text{ns}$
Rise time	$t_r$		-	250	-	
Turn-off delay time	$t_{d(off)}$		-	110	-	
Fall time	$t_f$		-	140	-	
Total gate charge	$Q_g$	$V_{DD}=80\text{V}, V_{GS}=10\text{V}$ $I_D=50\text{A}$	-	75	83	$\text{nC}$
Gate-source charge	$Q_{gs}$		-	13	15	
Gate-drain charge	$Q_{gd}$		-	36	40	

## Source-Drain Diode Ratings and Characteristics ( $T_C=25^\circ\text{C}$ unless otherwise noted)

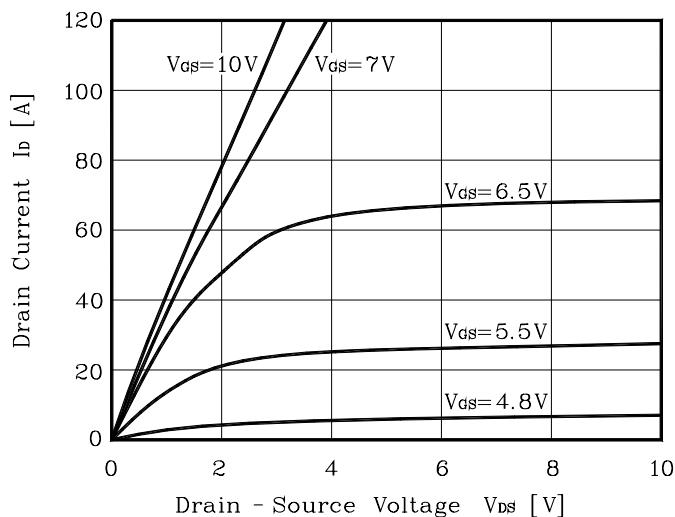
Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current	$I_S$	Integral reverse diode in the MOSFET	-	-	50	A
Source current (Pulsed) ①	$I_{SM}$		-	-	150	
Forward voltage ④	$V_{SD}$	$V_{GS}=0\text{V}, I_S=50\text{A}$	-	-	1.5	V
Reverse recovery time	$t_{rr}$	$I_S=50\text{A}, V_{GS}=0\text{V}$ $dI_F/dt=100\text{A}/\mu\text{s}$	-	100	-	ns
Reverse recovery charge	$Q_{rr}$		-	380	-	$\mu\text{C}$

Note :

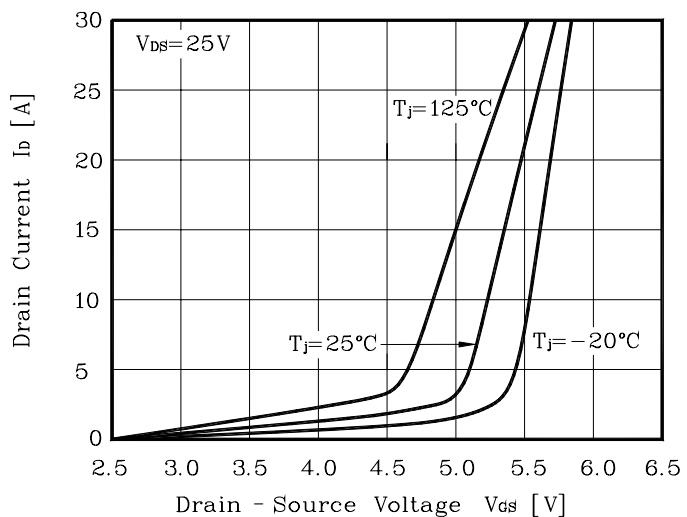
- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ②  $L=0.5\text{mH}, I_{AS}=25\text{A}, V_{DD}=10\text{V}, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
- ③ Pulse Test : Pulse Width  $\leq 300\text{us}$ , Duty cycle  $\leq 2\%$
- ④ Essentially independent of operating temperature

## Electrical Characteristic Curves

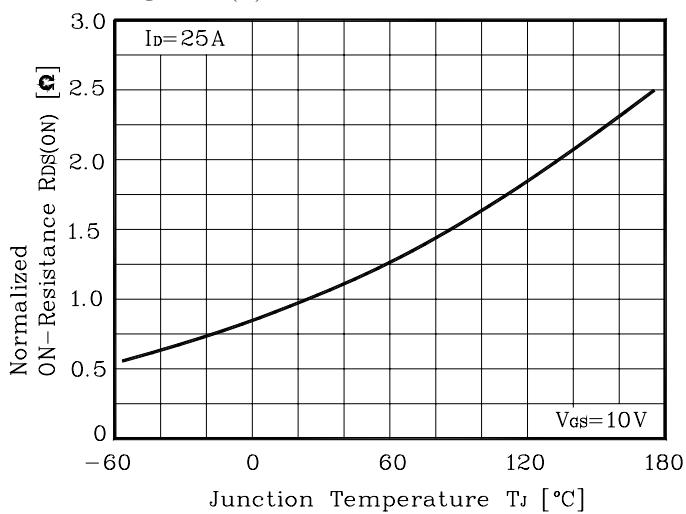
**Fig. 1  $I_D$  -  $V_{DS}$**



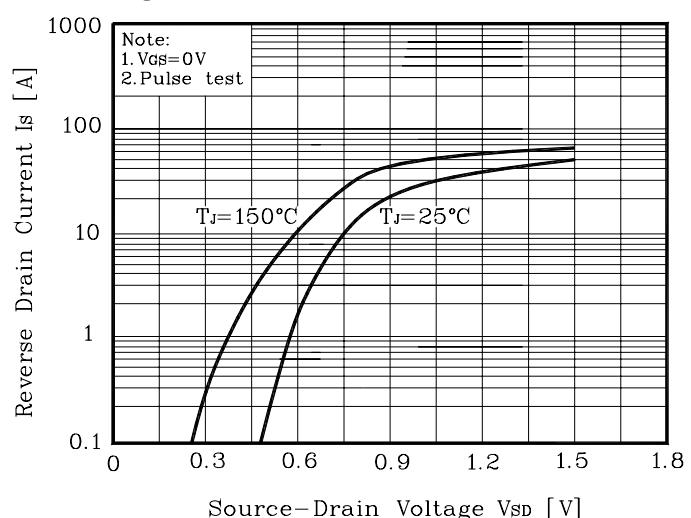
**Fig. 2  $I_D$  -  $V_{GS}$**



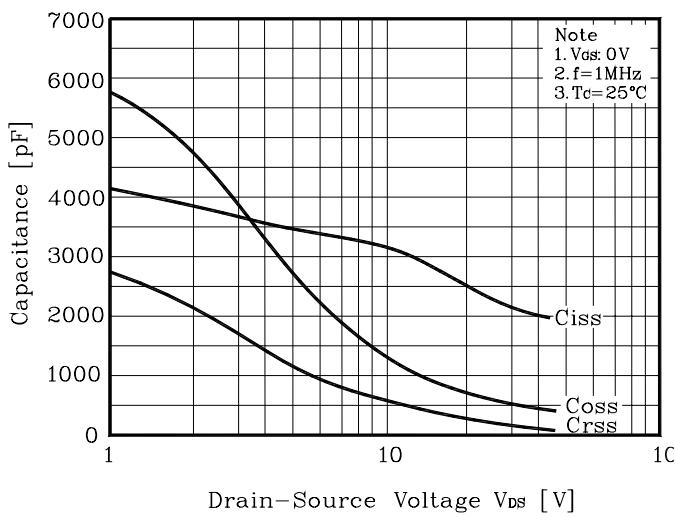
**Fig. 3  $R_{DS(on)}$  -  $I_D$**



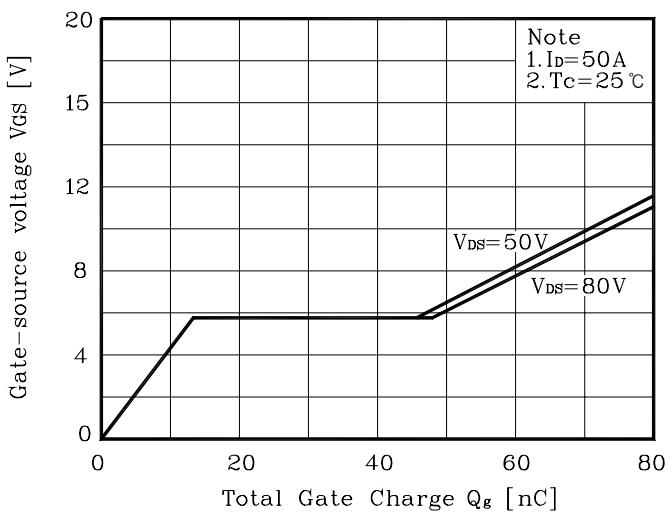
**Fig. 4  $I_S$  -  $V_{SD}$**



**Fig. 5 Capacitance -  $V_{DS}$**

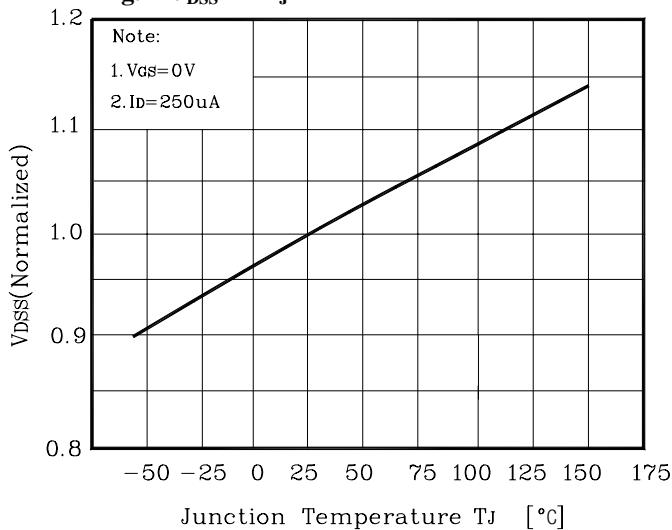


**Fig. 6  $V_{GS}$  -  $Q_G$**

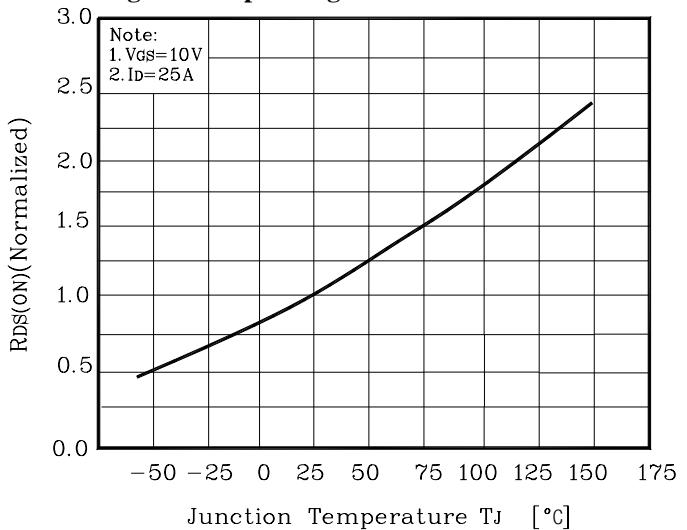


## Electrical Characteristic Curves

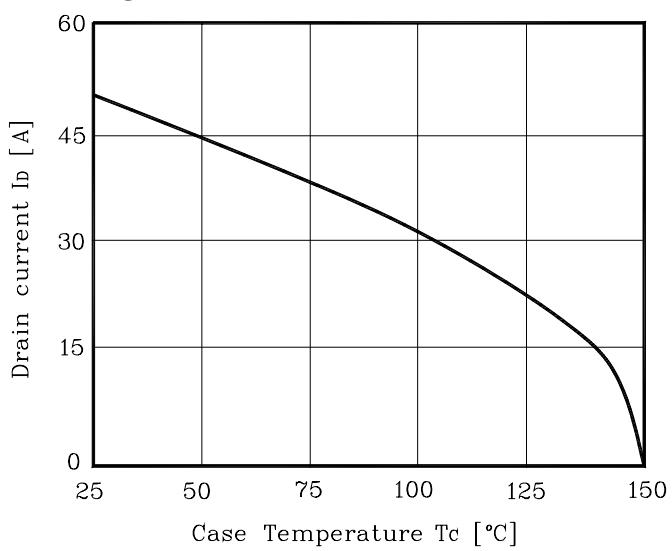
**Fig. 7  $V_{DSS}$  -  $T_J$**



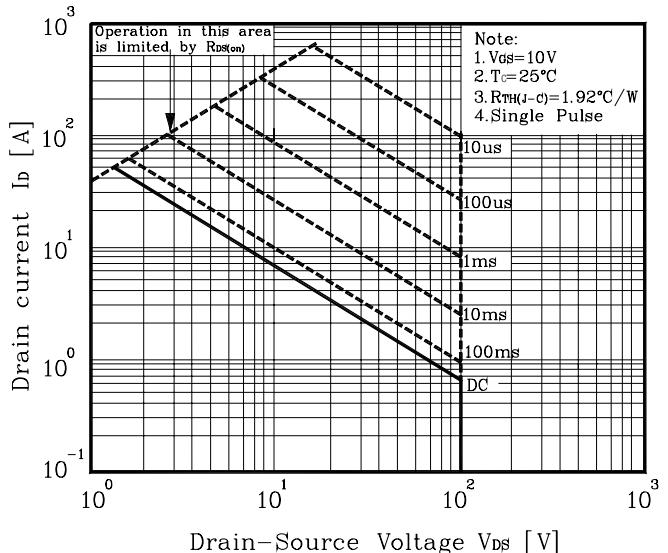
**Fig.8 Safe Operating Area**



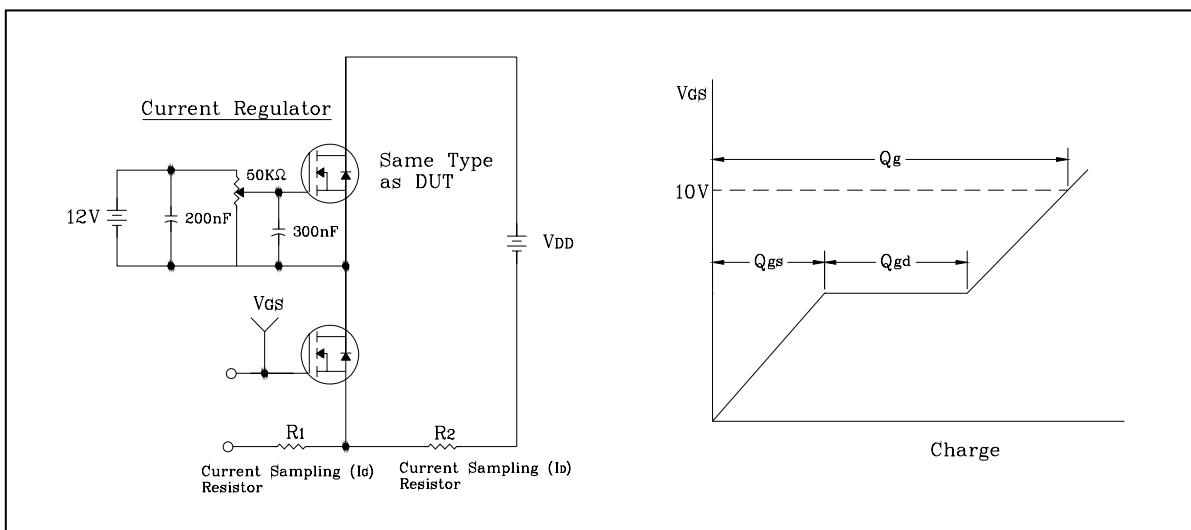
**Fig. 9  $I_D$  -  $T_C$**



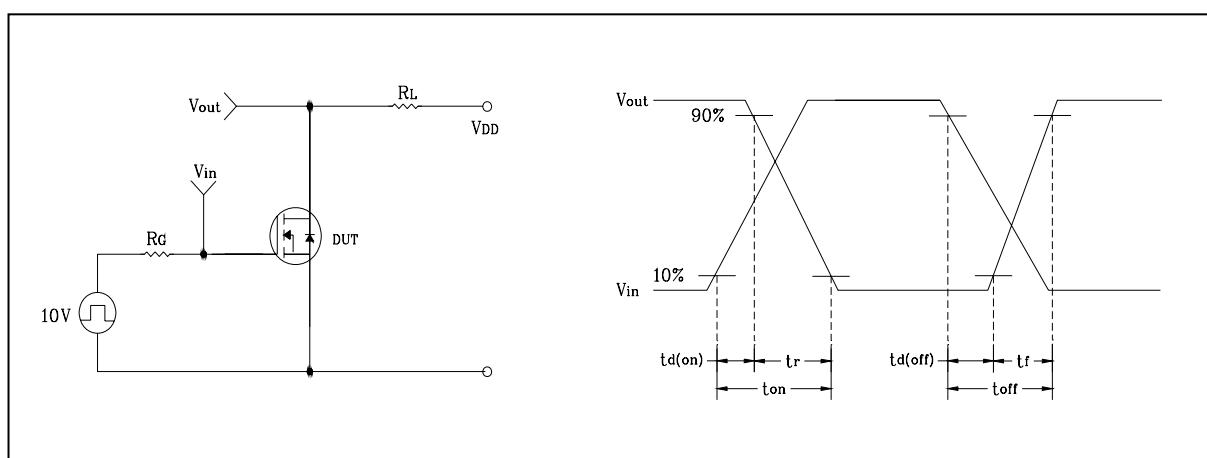
**Fig.10 Safe Operating Area**



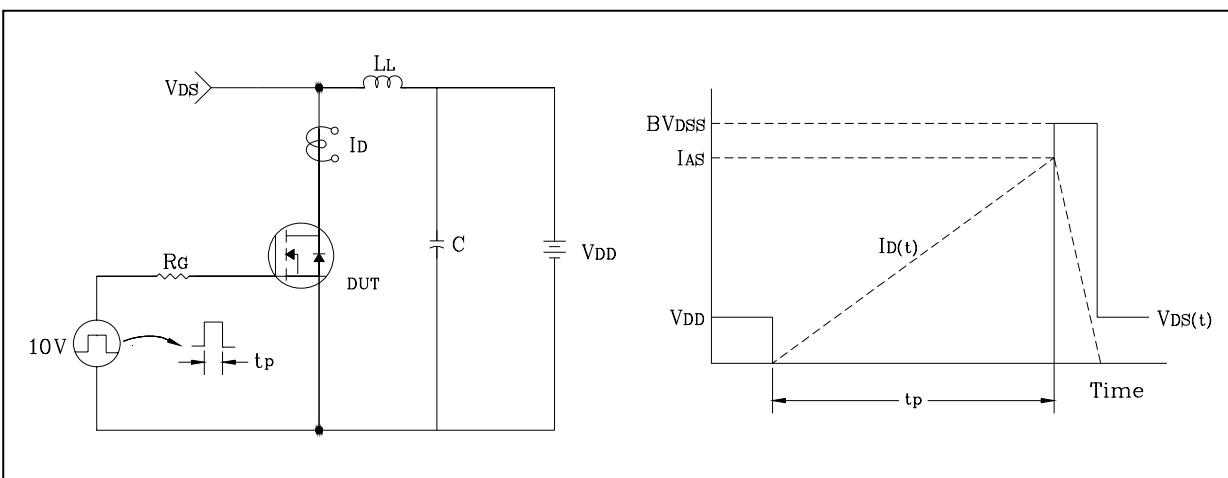
**Fig. 11 Gate Charge Test Circuit & Waveform**



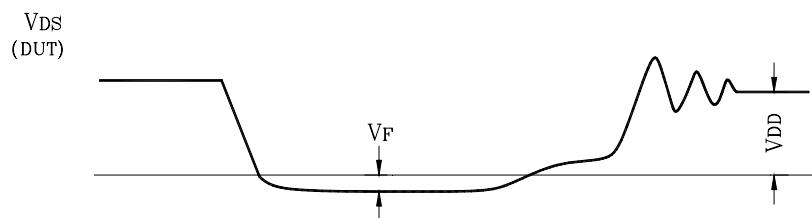
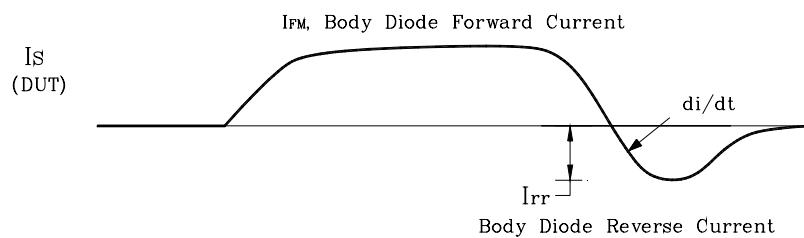
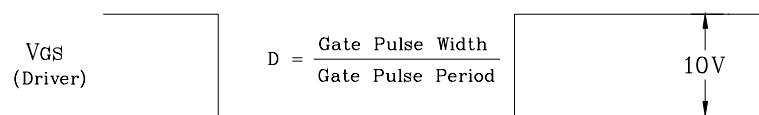
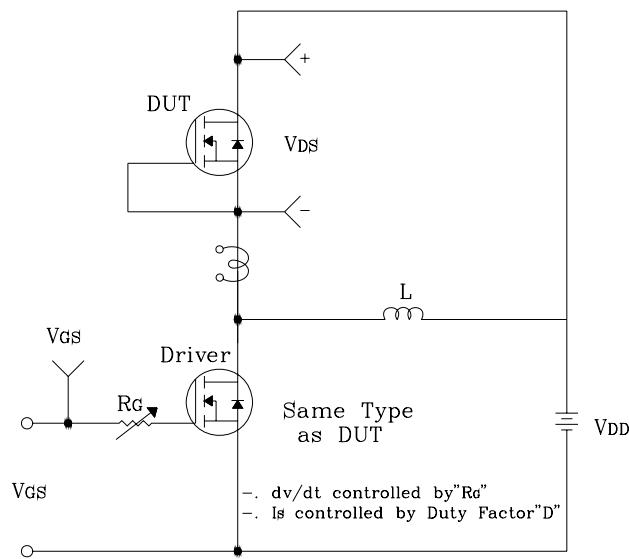
**Fig. 12 Resistive Switching Test Circuit & Waveform**



**Fig. 13 E<sub>AS</sub> Test Circuit & Waveform**

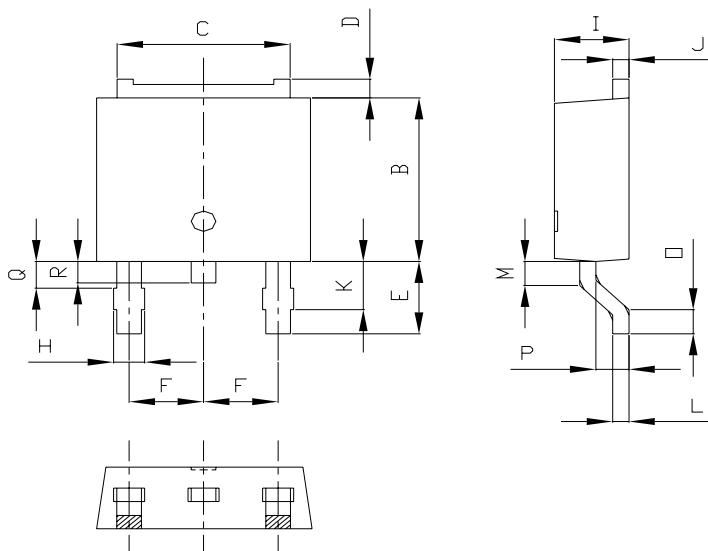


**Fig. 14 Diode Reverse Recovery Time Test Circuit & Waveform**

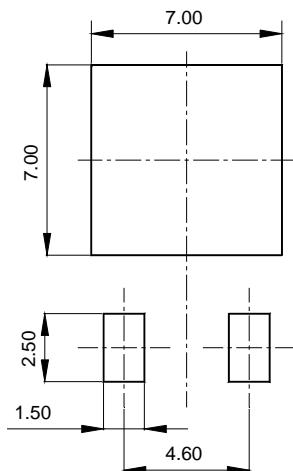


**Outline Dimension**

unit : mm



SYMBOL	MILLIMETERS			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
A	6.40	6.60	6.80	
B	5.90	6.10	6.30	
C	5.04	5.34	5.64	
D	0.50	0.70	0.90	
E	2.50	2.70	2.90	
F	2.10	2.30	2.50	
H	0.96 MAX			
I	2.20	2.30	2.40	
J	0.40	0.50	0.60	
K	1.60	1.80	2.00	
L	0.40	0.50	0.60	
M	0.81	0.91	1.01	
O	0.80	0.90	1.00	
P	0.90	1.00	1.10	
Q	0.95 MAX			
R	0.60	0.80	1.00	

**Recommended Land Pattern [unit: mm]**

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